



BAS16VVQ

SURFACE MOUNT SWITCHING DIODE ARRAY

Features

- Fast Switching Speed
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Fast Reverse Recovery: Maximum of 4ns
- Low Capacitance: Maximum of 1.5pF
- Low Leakage Current
- Triple Isolated Fast Switching Diode Array
- Ultra-Small Surface Mount Package
- Thermally Efficient Copper Alloy Leadframe for High Power
 Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The BAS16VVQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

Mechanical Data

- Package: SOT563
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper Alloy leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (C)
- Weight: 0.003 grams (approximate)



Ordering Information (Note 4)

Part Number	Compliance	Pookogo	Packing		
Part Number	Compliance	Package	Qty.	Carrier	
BAS16VVQ-7	Automotive	SOT563	3000	Tape & Reel	

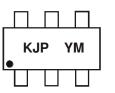
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



KJP = Product Type Marking Code YM = Date Code Marking Y = Year (ex: I = 2021) M = Month (ex: 9 = September)

Date Code Key

Notes:

Year	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	I	J	K	L	М	Ν	0	Р	R	S	Т	U
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings @ $T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit	
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V	
RMS Reverse Voltage	V _{R(RMS)}	71	V	
Forward Continuous Current (Note 5)	I _{FM}	200	mA	
Image: Non-Repetitive Peak Forward Surge CurrentImage: mail of t = 1.0 µs (mail t = 1.0 µs) (mail t = 1.0 µs) (mail t = 1.0 µs)Image: Non-Repetitive Peak Forward Surge CurrentImage: mail of t = 1.0 µs) (mail t = 1.0 µs) (mail t = 1.0 µs)		IFSM	4.0 1.0 0.5	A

Thermal Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{0JA}	357	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

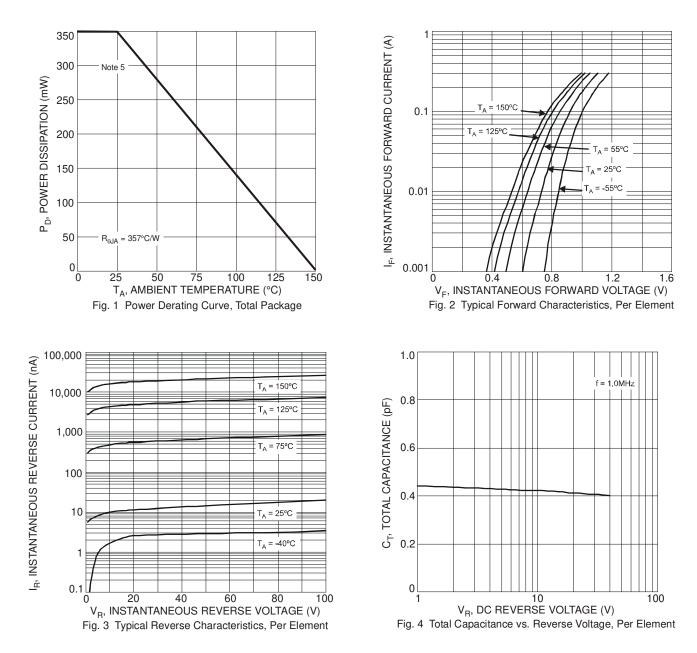
Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)		100		V	$I_R = 100 \mu A$
		_	0.715		I _F = 1.0mA
Forward Voltage		_	0.855		I _F = 10mA
Forward voltage	VF	_	1.0		$I_F = 50 \text{mA}$
		_	1.25		I _F = 150mA
		_	0.5	μA	V _R = 80V
Lookage Current (Note 6)		_	50	μA	$V_R = 80V, T_J = 150^{\circ}C$
Leakage Current (Note 6)	I _R	_	30	μA	V _R = 25V, T _J = 150°C
		_	30	nA	V _R = 25V
Total Capacitance	Ст	_	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	_	4.0	ns	$\begin{split} I_{\text{F}} &= I_{\text{R}} = 10\text{mA}, \\ I_{\text{rr}} &= 0.1 \text{ x } I_{\text{R}}, \text{ R}_{\text{L}} = 100\Omega \end{split}$

 Notes:
 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.

 6. Short duration pulse test used to minimize self-heating effect.

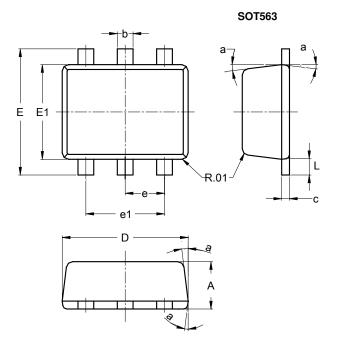






Package Outline Dimensions

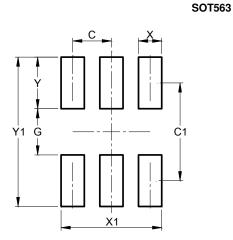
Please see http://www.diodes.com/package-outlines.html for the latest version.



1						
SOT563						
Dim	Min	Max	Тур			
Α	0.55	0.60				
b	0.15	0.30	0.20			
С	0.10	0.18	0.11			
D	1.50	1.70	1.60			
E	1.55	1.70	1.60			
E1	1.10	1.25	1.20			
е			0.50			
e1	0.90	1.10	1.00			
L	0.10	0.30	0.20			
а	8°	9°	7°			
All	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.500
C1	1.270
G	0.600
Х	0.300
X1	1.300
Y	0.670
Y1	1.940

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